
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wang et al.

Attorney Docket No.:
ALTRP100/A1198**RECEIVED
CENTRAL FAX CENTER****JAN 29 2008**

Application No.: 10/719,218

Examiner: Rao, Shrinivas H.

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL, AND DESIGN
FOR ASSEMBLING A LOW-K SI DIE TO
ACHIEVE AN INDUSTRIAL GRADE
RELIABILITY WIRE BONDING PACKAGE

Confirmation No.: 3208

CERTIFICATE OF MAILINGI hereby certify that this correspondence is being sent via facsimile to (571)
273-8300 on January 29, 2008 to the Commissioner for Patents, P.O. Box
1450 Alexandria, VA 22313-1450

Signed: _____

Jonathan Scott

AMENDMENT FMail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated October 29, 2007, please amend the above-identified patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begin on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.